

Patent Abstracts of Japan

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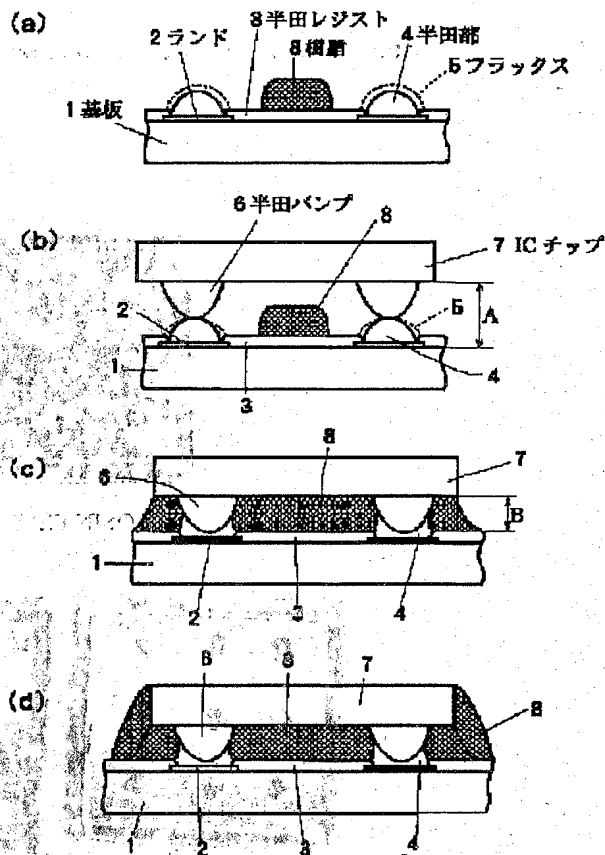
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TITLE : FLIP-CHIP-MOUNTING METHOD



ABSTRACT : PURPOSE: To reduce the number of processes and cost in flip-chip mounting and to improve the mounting reliability.

CONSTITUTION: A land 2 formed on a substrate 1 is covered with a solder part 4, resin 8 is applied to the surface other than the solder part 4 of the substrate 1, flux 5 is applied to the surface of the solder part 4, and then an IC chip 7 is mounted to the solder part 4, and then the soldering by heating and the filling of the resin 8 are performed simultaneously.

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